

L Number	Hits	Search Text	DB	Time stamp
1	184	(semiconductor or die or chip or IC) same heat near shield	USPAT	2004/09/23 23:06
2	97	(semiconductor or die or chip or IC) with heat near shield	USPAT	2004/09/23 23:09
3	92	(semiconductor or die or chip or IC) with heat adj shield	USPAT	2004/09/23 23:15
-	1	"20040061213"	USPAT; US-PGPUB	2004/09/22 16:24
-	3510	257/678	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/21 19:41
-	1194	257/685	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/21 19:57
-	2773	257/686	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/21 20:37
-	2458	257/706	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/21 21:08
-	1157	257/720	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 10:50
-	3775	257/723	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 11:09
-	2547	257/777	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 11:32
-	4116	257/778	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 12:15
-	2643	257/784	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2004/09/22 13:47
-	5	5550711.pn. 5898219.pn. 6201302.pn. 6489676.pn. 6538319.pn. 6737750.pn.	USPAT	2004/09/22 13:38
-	2	5373189.pn. 6075289.pn.	USPAT	2004/09/22 13:44

-	12	6274930.pn. 6340846.pn. 6376904.pn. 6388313.pn. 6400007.pn. 6414381.pn. 6424050.pn. 20020004258.pn. 20020014689.pn. 20020125557.pn. 20020125558.pn. 20020130404.pn.	USPAT; US-PGPUB	2004/09/22 13:44
-	4700	257/787	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:06
-	951	438/122	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 14:22
-	2154	438/108	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:11
-	1018	438/109	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:23
-	3797	361/760	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 15:29
-	25	"6316838"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/22 16:11
-	1		USPAT	2004/09/22 15:32
-	1		USPAT	2004/09/22 15:33
-	1		USPAT	2004/09/22 15:33
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-	1		USPAT	2004/09/22 15:36
-	1		USPAT	2004/09/22 15:36
-	1		USPAT	2004/09/22 15:36
-	1		USPAT	2004/09/22 15:41
-	1		USPAT	2004/09/22 15:42
-	1		USPAT	2004/09/22 15:42
-	1		USPAT	2004/09/22 15:43
-	1		USPAT	2004/09/22 15:43
-	1		USPAT	2004/09/22 15:43
-	0	"electromagnetic near shield" same heat near (spread\$3 or sink or transfer or dissipation)	USPAT; US-PGPUB	2004/09/22 16:25
-	535	((electromagnetic or electrical) near shield) and heat near (spread\$3 or sink or transfer or dissipation)	USPAT; US-PGPUB	2004/09/22 16:47
-	131	((electromagnetic or electrical) near shield) same heat near (spread\$3 or sink or transfer or dissipation)	USPAT; US-PGPUB	2004/09/22 16:27

-	13	((electromagnetic or electrical) near shield) same heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) near (chip or die or IC or semiconductor)	USPAT; US-PGPUB	2004/09/22 16:40
-	0	((electromagnetic or electrical) near shield) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) near (chip or die or IC or semiconductor)	USPAT	2004/09/22 16:42
-	0	((electromagnetic or electrical) near shield) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) near (chip or die or IC or semiconductor)	USPAT	2004/09/22 16:43
-	12	((electromagnetic or electrical) near shield) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) with (chip or die or IC or semiconductor)	USPAT	2004/09/22 16:48
-	1884	((electromagnetic or electrical or EMI) near shield\$3) and heat near (spread\$3 or sink or transfer or dissipation)	USPAT; US-PGPUB	2004/09/22 17:02
-	52	((electromagnetic or electrical or EMI) near shield\$3) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) with (chip or die or IC or semiconductor)	USPAT	2004/09/22 17:01
-	6	((electromagnetic or electrical or EMI) near shield\$3) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) near (chip or die or IC or semiconductor)	USPAT	2004/09/22 17:03
-	4024	((electromagnetic or electrical or EMI) with shield\$3) and heat near (spread\$3 or sink or transfer or dissipation)	USPAT; US-PGPUB	2004/09/22 17:23
-	9	((electromagnetic or electrical or EMI) with shield\$3) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) near (chip or die or IC or semiconductor)	USPAT	2004/09/22 17:23
-	105	((electromagnetic or electrical or EMI) with shield\$3) and heat near (spread\$3 or sink or transfer or dissipation)) and ("RF" or radio near frequency) with (chip or die or IC or semiconductor)	USPAT	2004/09/22 17:22
-	10411	((electromagnetic or electrical or EMI) with shield\$3) and heat	USPAT	2004/09/22 17:23
-	13	((electromagnetic or electrical or EMI) with shield\$3) and heat) and ("RF" or radio near frequency) near (chip or die or IC or semiconductor)	USPAT	2004/09/23 13:33
-	0	embedded near ground near plane same heat near dissipation and ground near plane with electrical near shield\$3	USPAT	2004/09/23 13:35
-	7	ground near plane same heat near dissipation and ground near plane with electrical near shield\$3	USPAT	2004/09/23 13:53
-	14	ground near plane same heat and ground near plane with electrical near shield\$3	USPAT	2004/09/23 14:06
-	30	ground near plane same heat and ground near plane same electrical near shield\$3	USPAT	2004/09/23 14:29
-	30	ground near (plane or layer or film or plate) same heat and ground near plane same electrical near shield\$3	USPAT	2004/09/23 14:29
-	65	ground near (plane or layer or film or plate) and heat and ground near plane same electrical near shield\$3	USPAT	2004/09/23 14:29
-	32	ground near (plane or layer or film or plate) same heat and ground near (plane or layer or film or plate) same electrical near shield\$3	USPAT	2004/09/23 14:37

-	29	ground near (plane or layer or film or plate) and heat near dissipat\$3 and ground near (plane or layer or film or plate) same electrical near shield\$3	USPAT	2004/09/23 14:37
-	63	ground near (plane or layer or film or plate) and heat near dissipat\$3 and ground near (plane or layer or film or plate) same (electrical or electro\$5 or EMI) near shield\$3	USPAT	2004/09/23 14:38
-	15	ground near (plane or layer or film or plate) same heat near dissipat\$3 and ground near (plane or layer or film or plate) same (electrical or electro\$5 or EMI) near shield\$3	USPAT	2004/09/23 14:43
-	30	ground near (plane or layer or film or plate) same heat near dissipat\$3 and ground near (plane or layer or film or plate) same (electrical or electro\$5 or EMI) with shield\$3	USPAT	2004/09/23 14:54
-	122	ground near (plane or layer or film or plate) same heat and ground near (plane or layer or film or plate) same (electrical or electro\$5 or EMI) with shield\$3	USPAT	2004/09/23 14:55
-	70	ground near (plane or layer or film or plate) with heat and ground near (plane or layer or film or plate) same (electrical or electro\$5 or EMI) with shield\$3	USPAT	2004/09/23 14:55
-	51	ground near (plane or layer or film or plate) with heat and ground near (plane or layer or film or plate) with (electrical or electro\$5 or EMI) with shield\$3	USPAT	2004/09/23 15:02
-	71	(ground near (plane or layer or film or plate) same heat and ground near (plane or layer or film or plate) same (electrical or electro\$5 or EMI) with shield\$3) not (ground near (plane or layer or film or plate) with heat and ground near (plane or layer or film or plate) with (electrical or electro\$5 or EMI) with shield\$3)	USPAT	2004/09/23 15:09